

FIG. 1 (PRIOR ART)

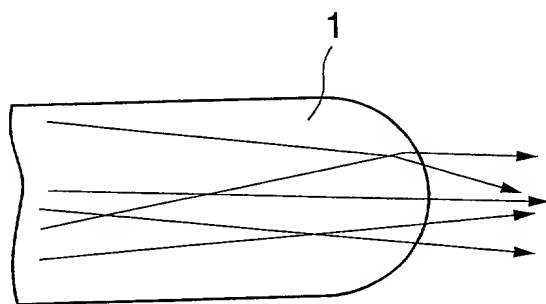


FIG. 2 (PRIOR ART)

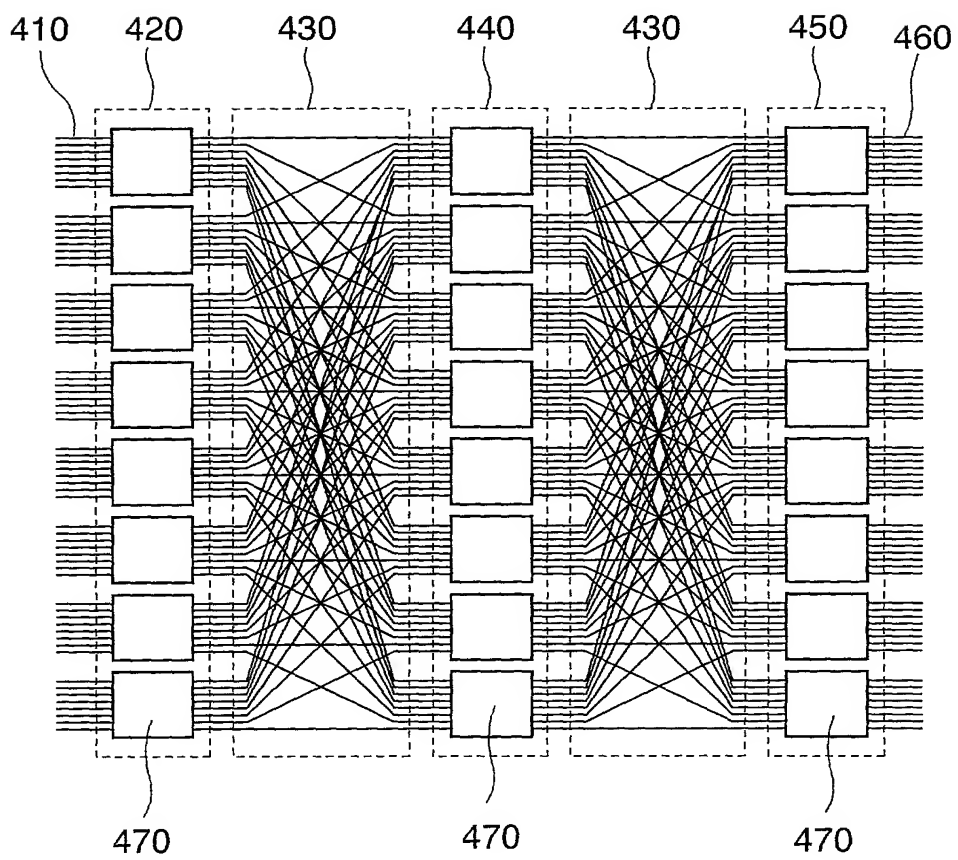


FIG. 3A  
(PRIOR ART)

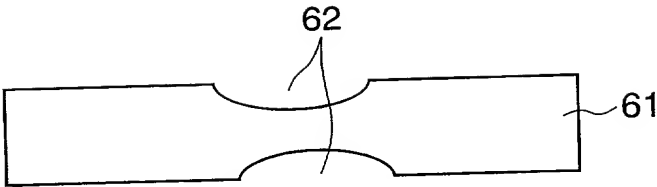


FIG. 3B  
(PRIOR ART)

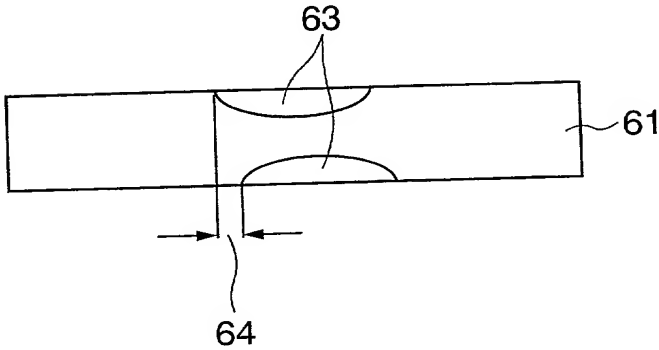


FIG. 4 (PRIOR ART)

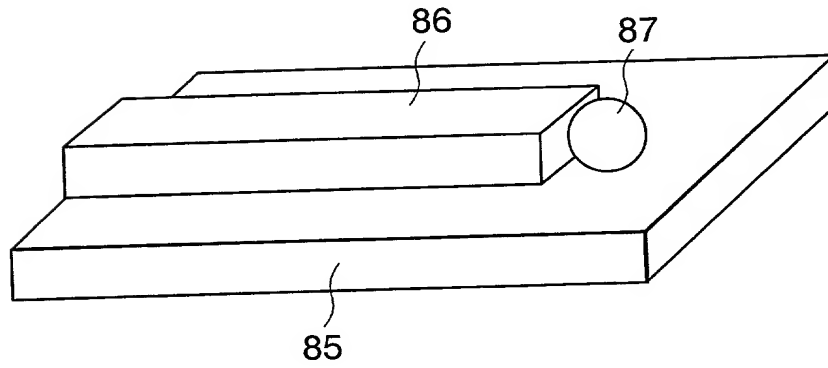


FIG. 5 (PRIOR ART)

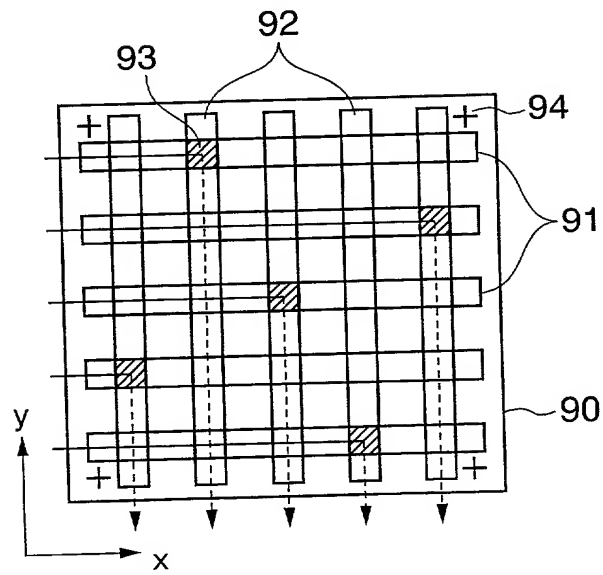


FIG. 6 (PRIOR ART)

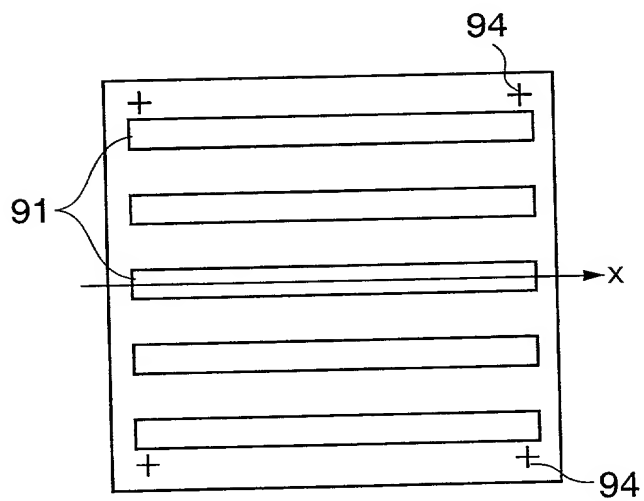


FIG. 7 (PRIOR ART)

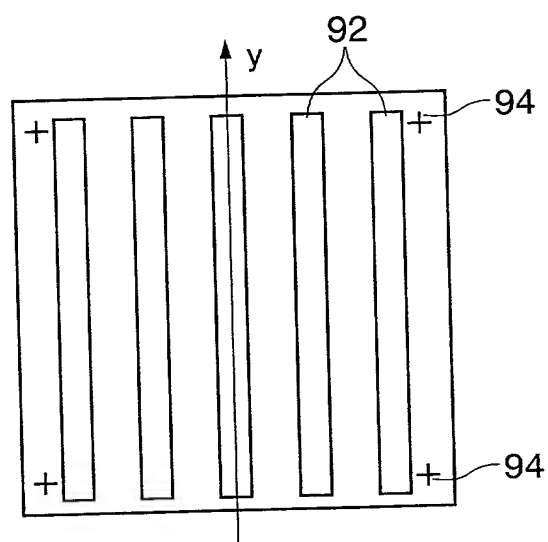


FIG. 8 (PRIOR ART)

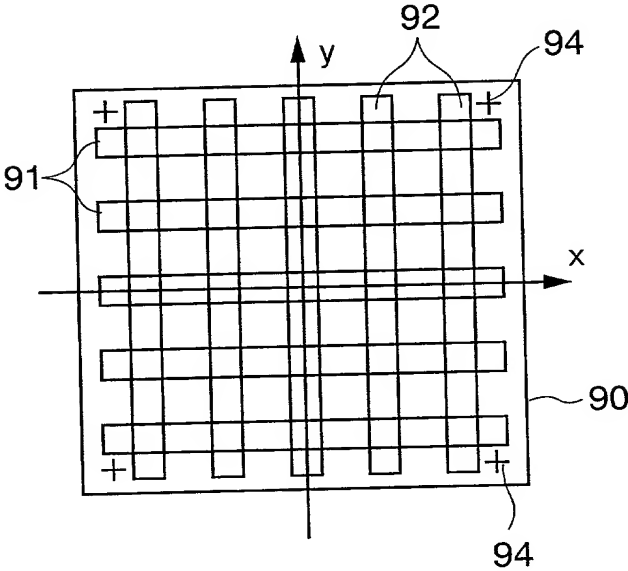




FIG. 9

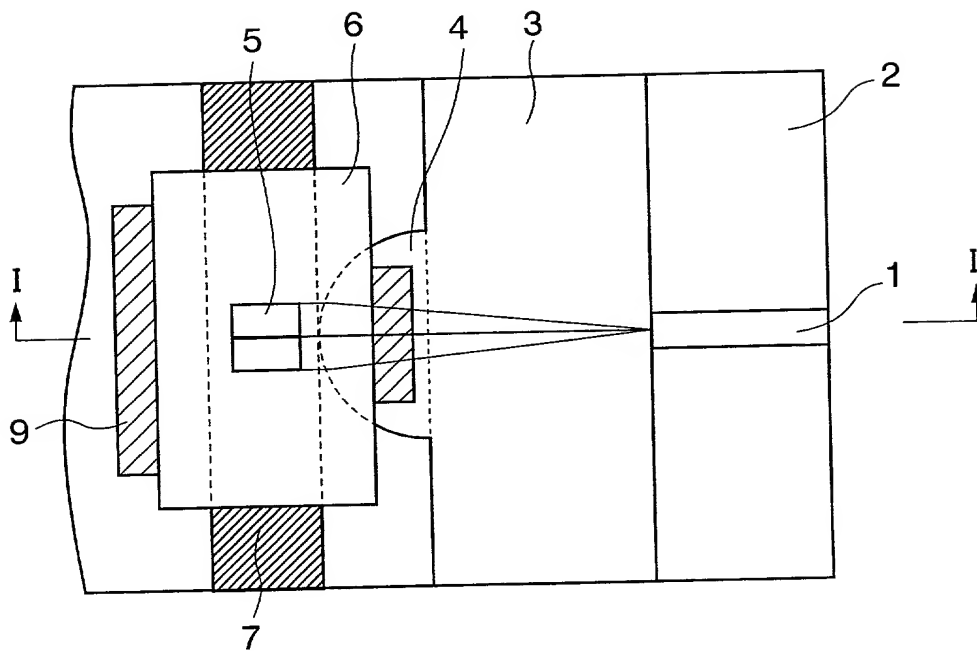


FIG. 10

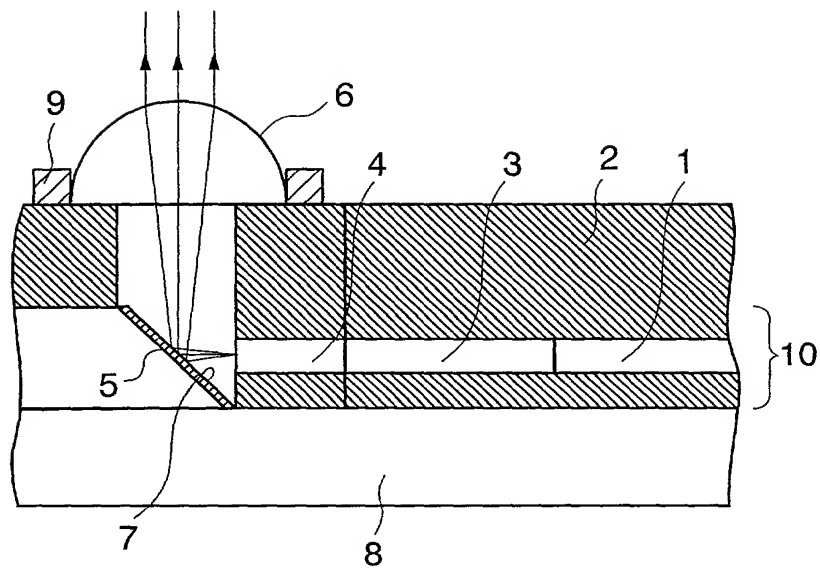


FIG. 11

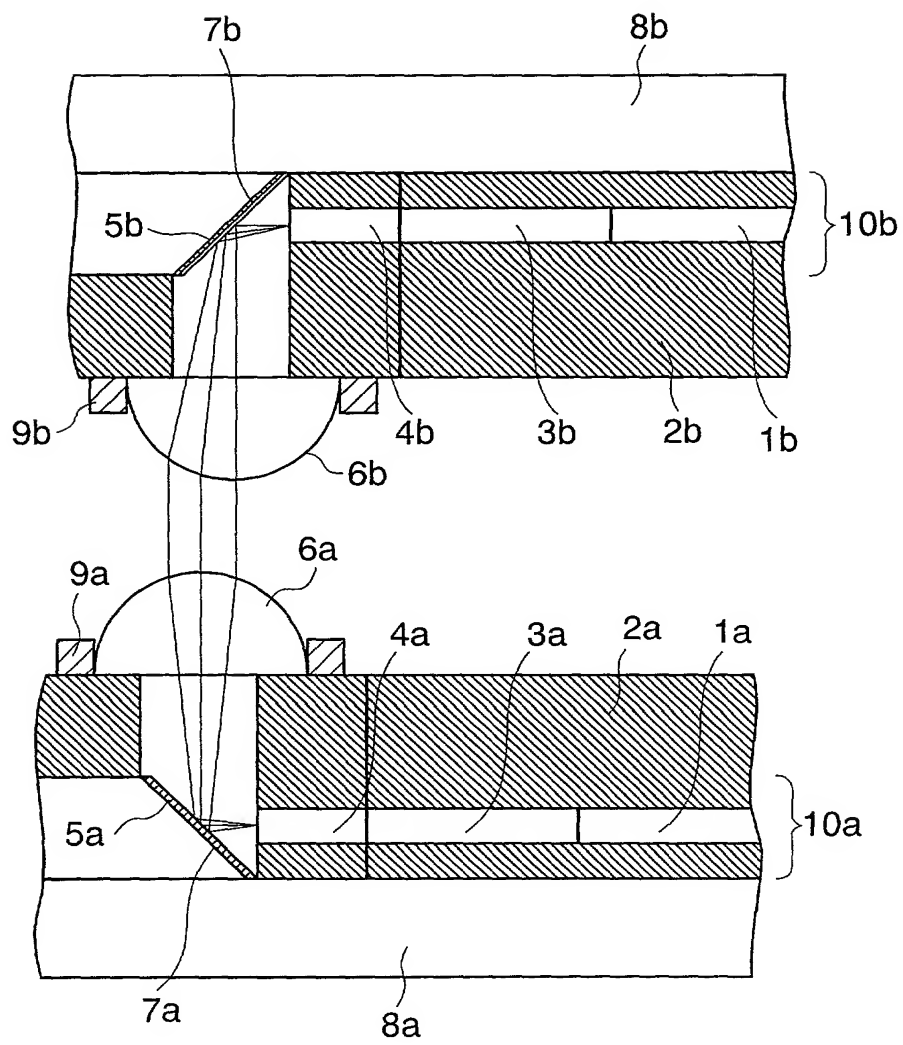


FIG. 12

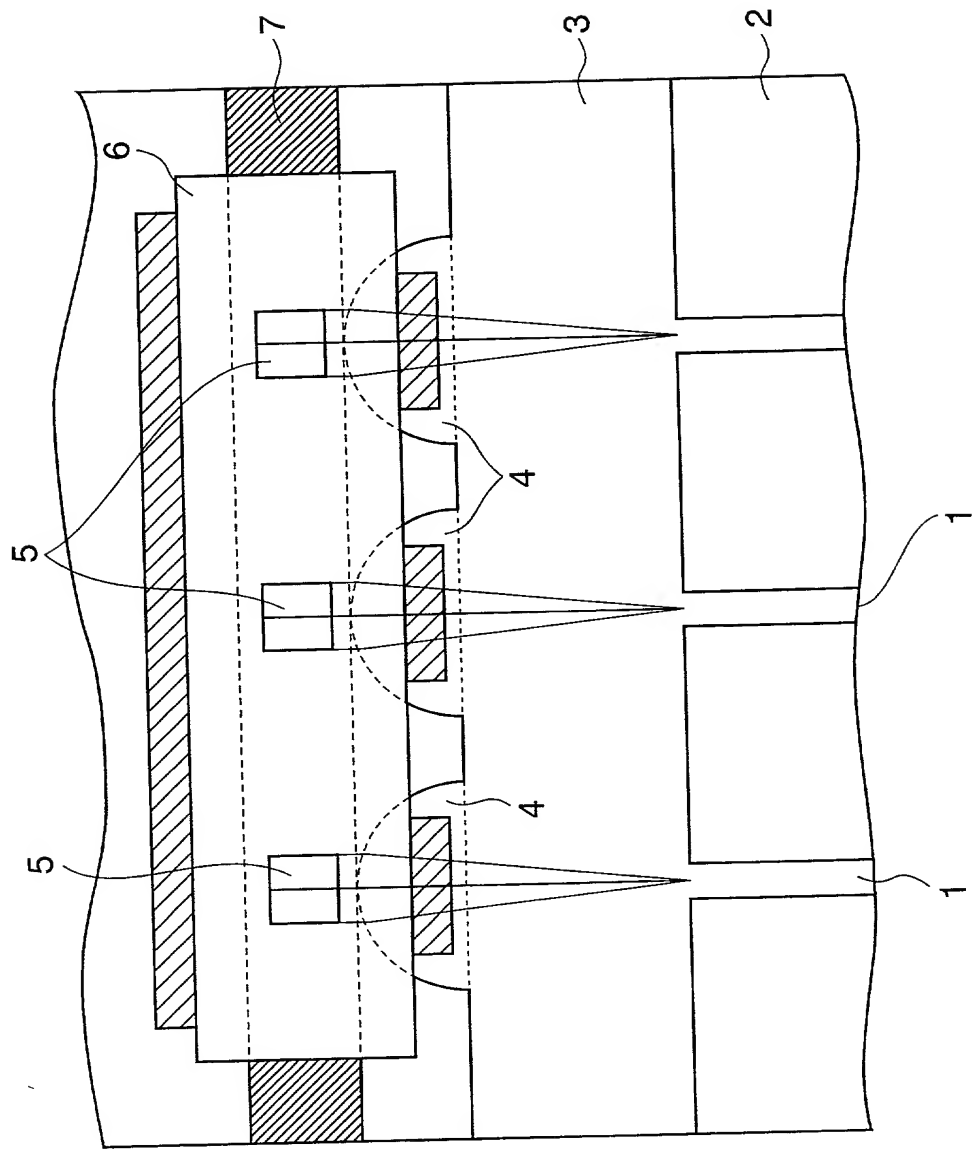


FIG. 13

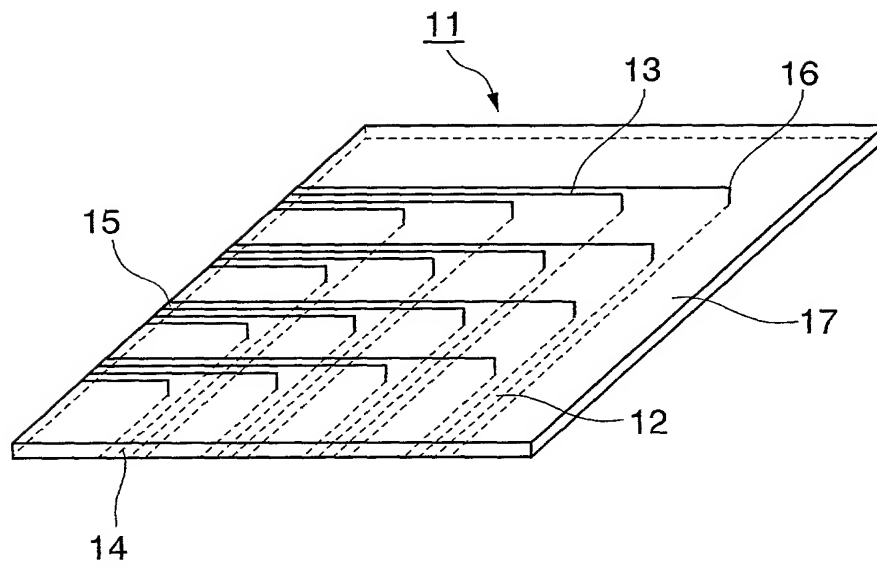


FIG. 14

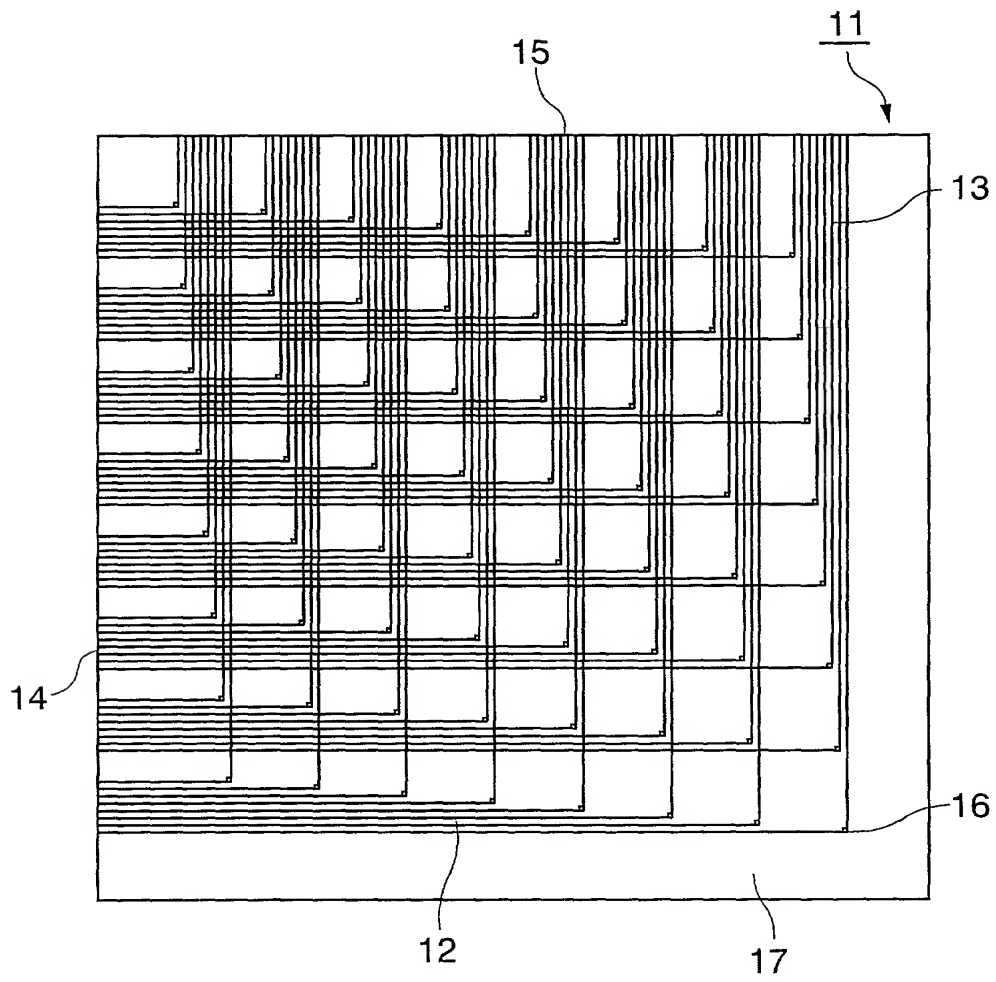


FIG. 15

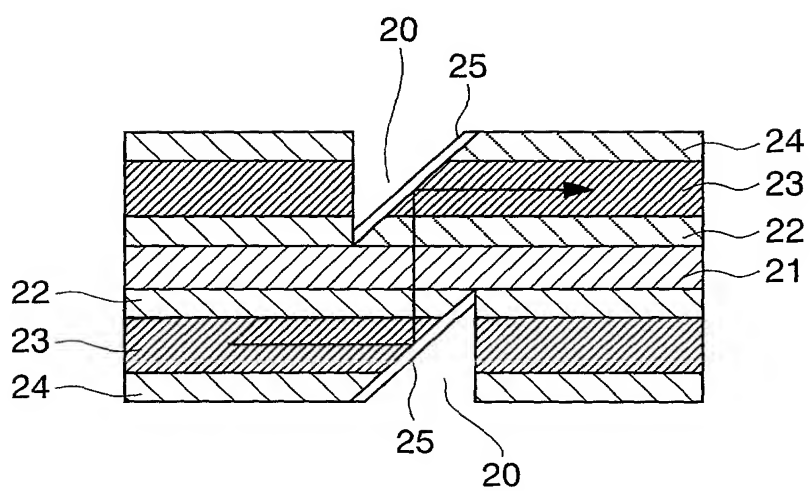


FIG. 16A

FIG. 16A

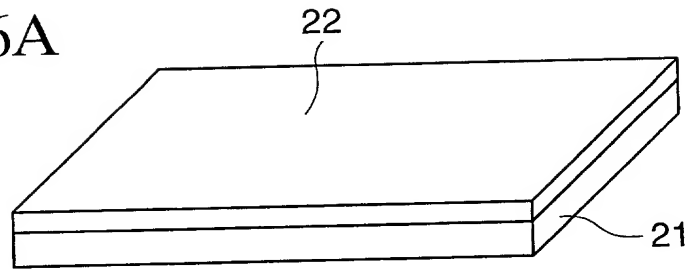


FIG. 16B

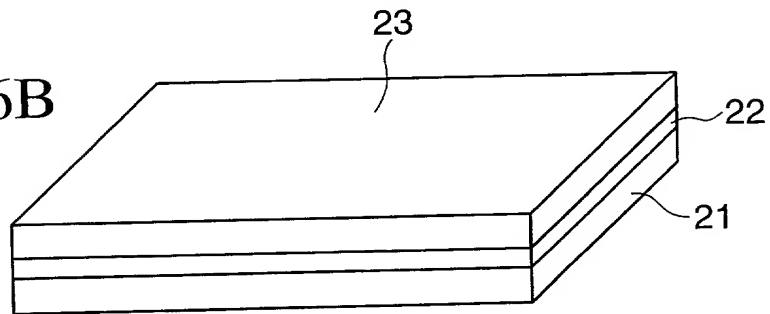


FIG. 16C

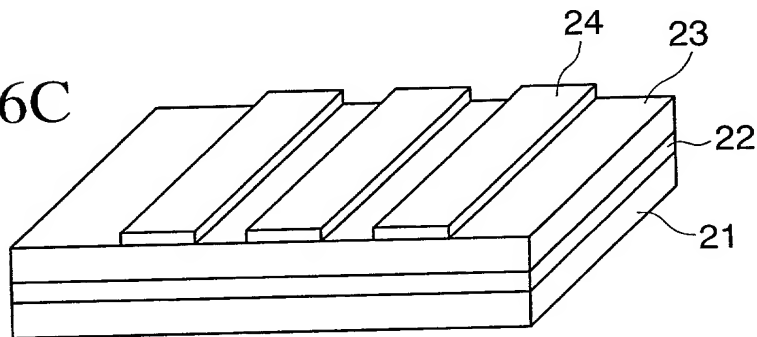


FIG. 16D

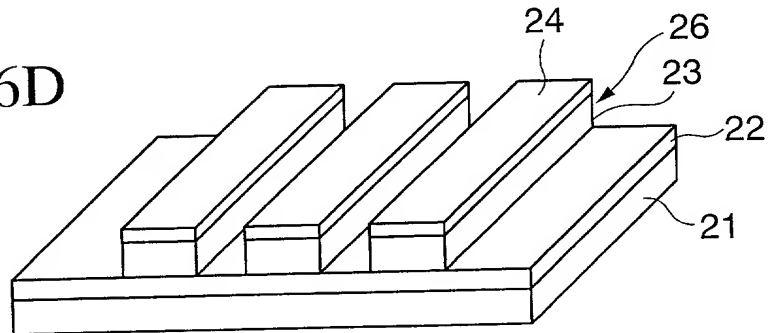




FIG. 16E

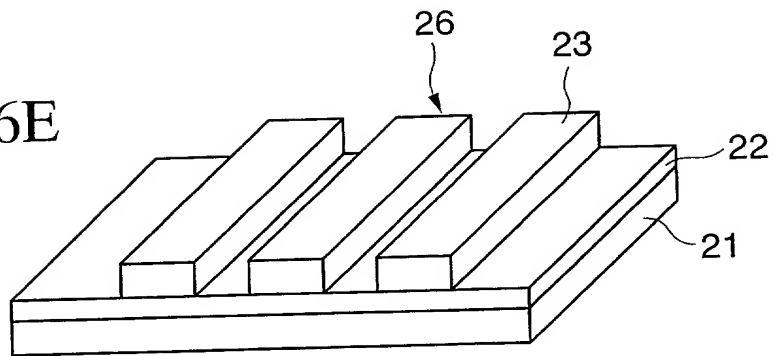


FIG. 16F

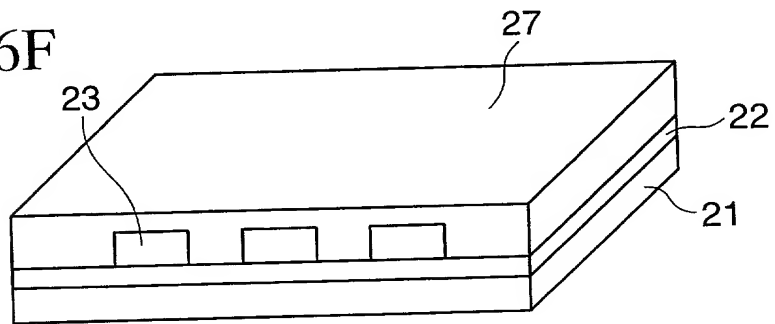


FIG. 16G

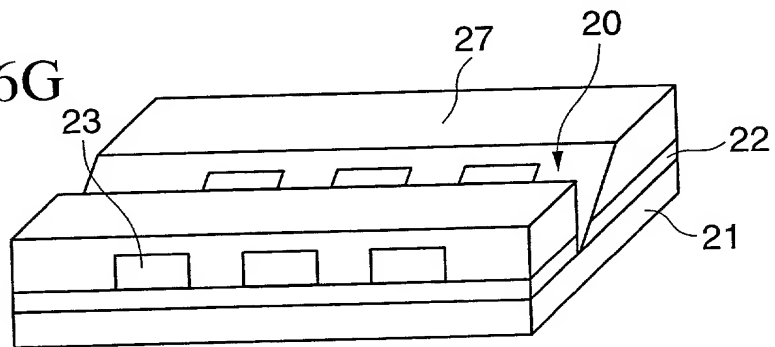


FIG. 16H

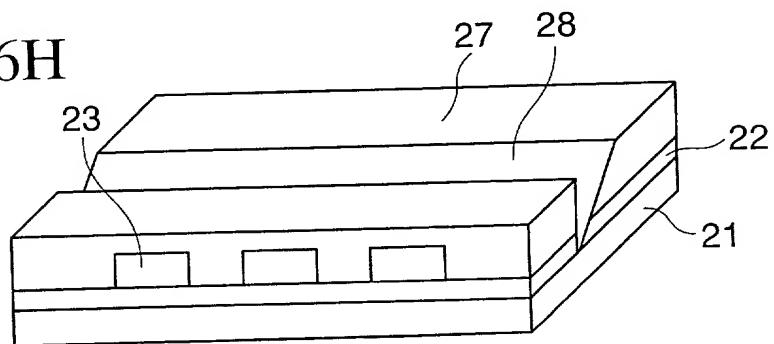


FIG. 17

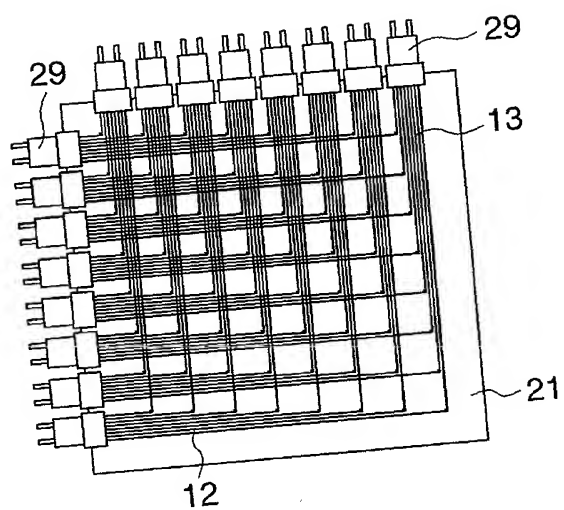


FIG. 18

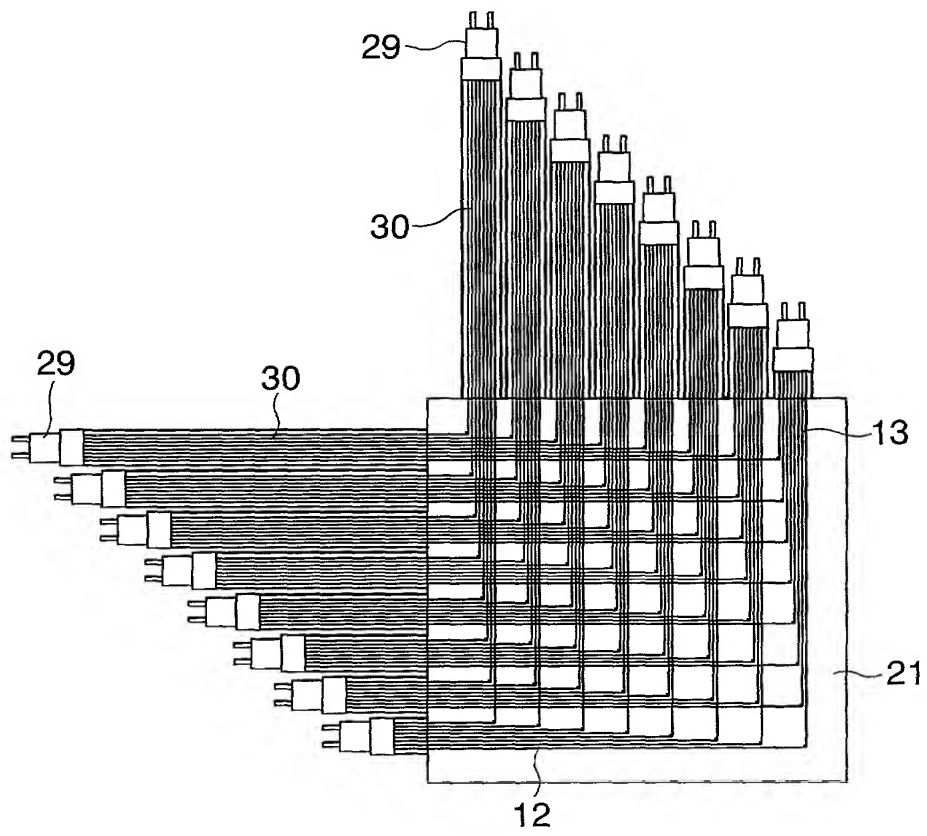


FIG. 19A

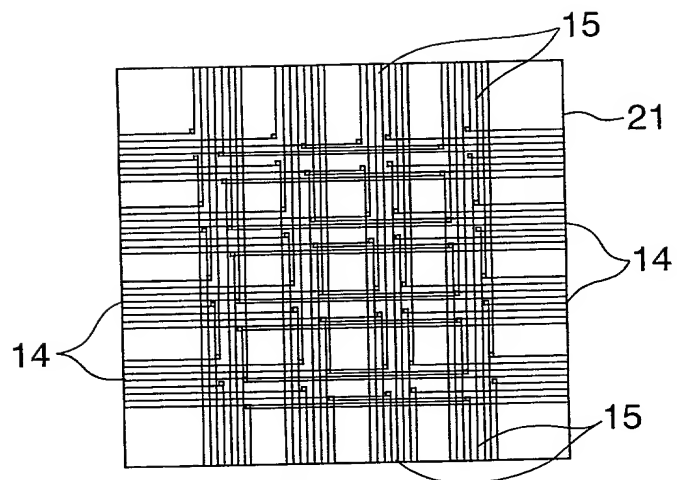


FIG. 19B

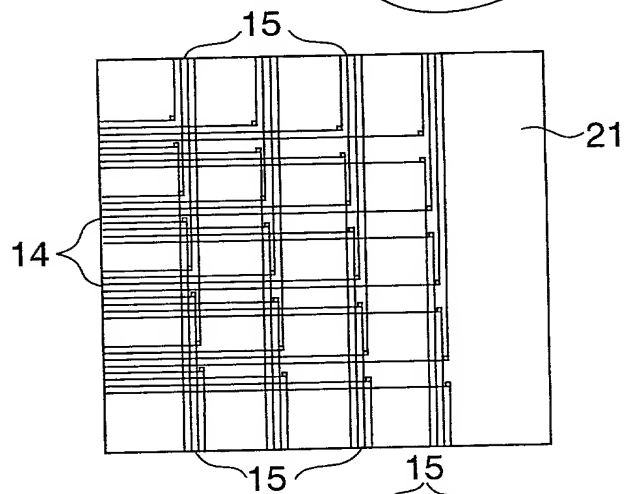


FIG. 19C

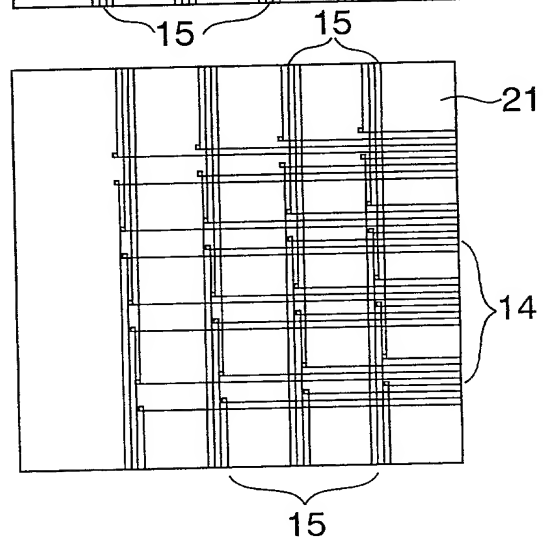


FIG. 20

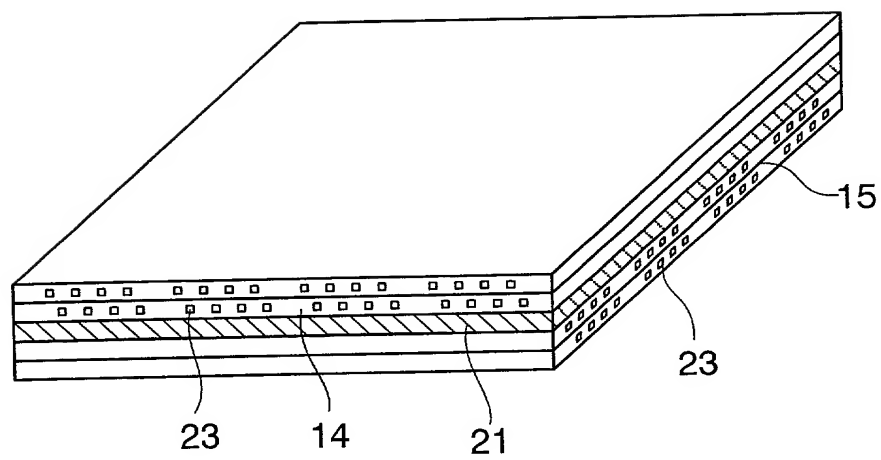


FIG. 21

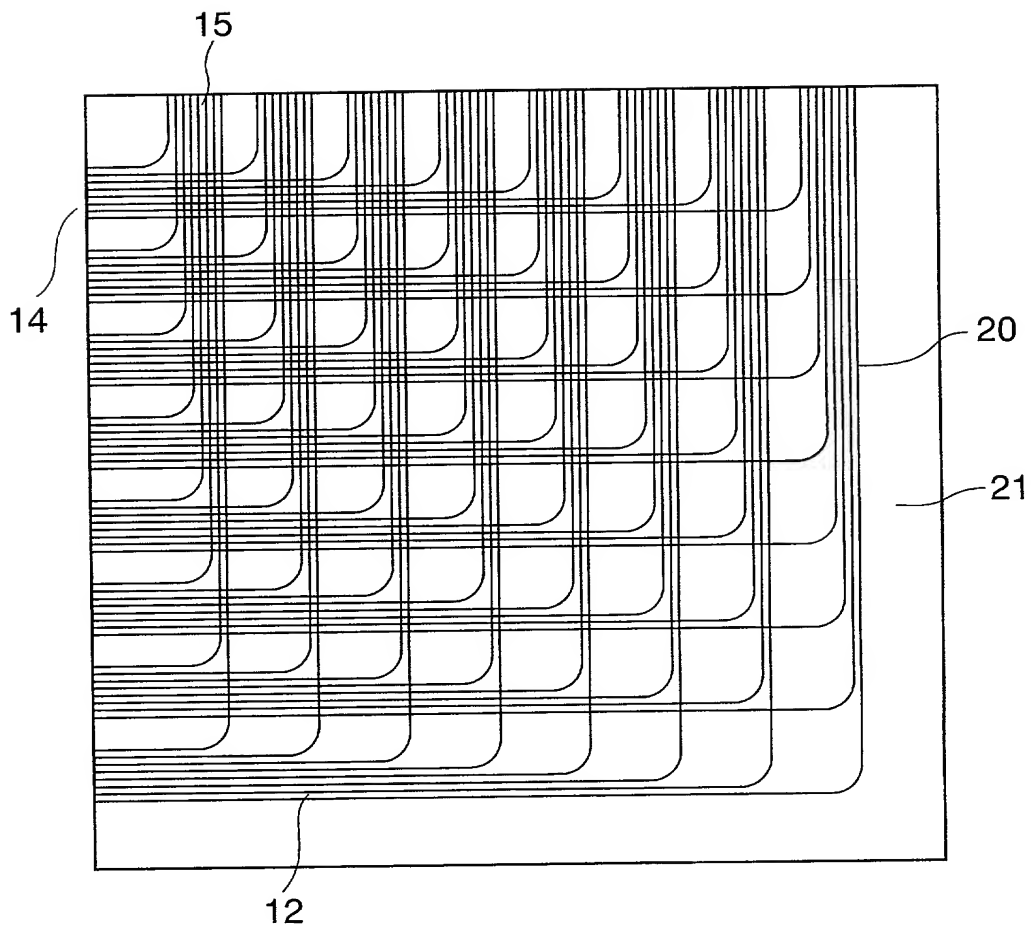


FIG. 22A

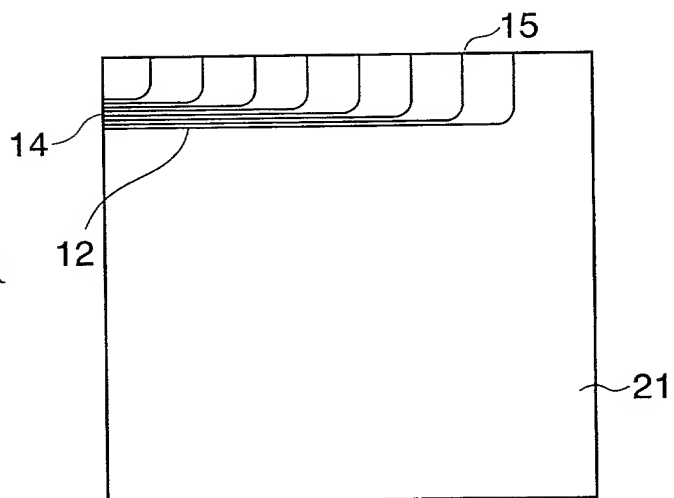


FIG. 22B

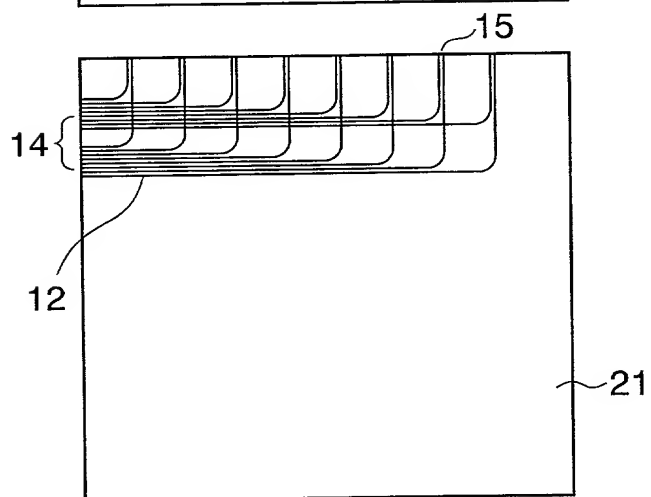


FIG. 22C

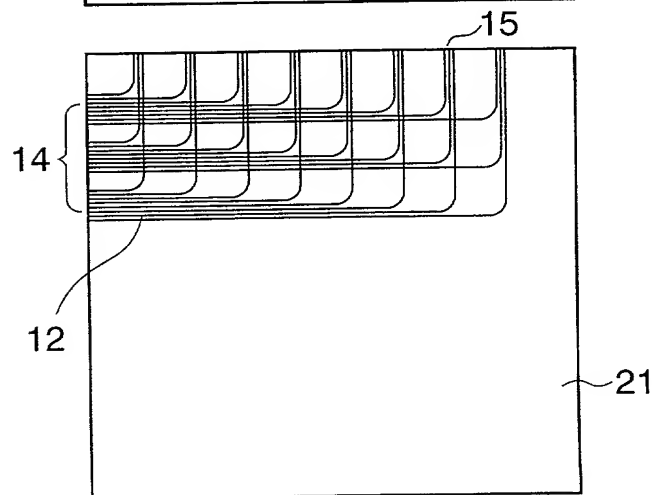


FIG. 23

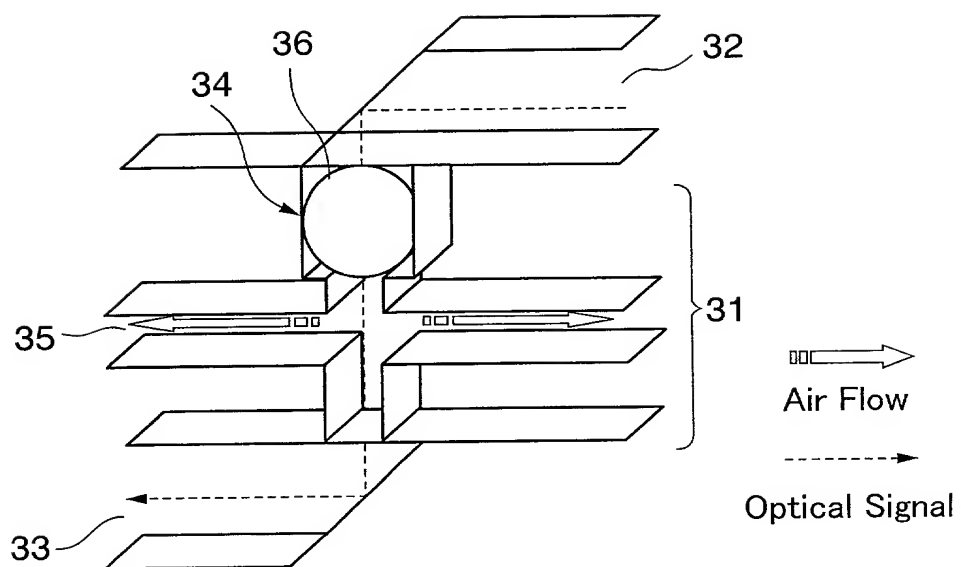




FIG. 24

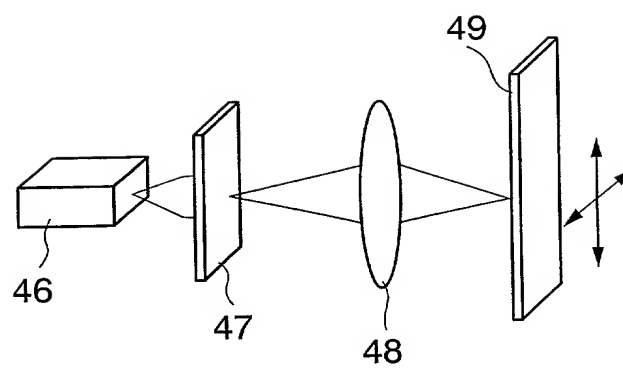


FIG. 25

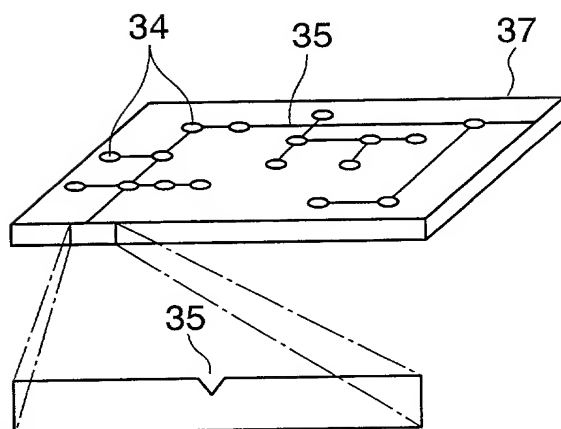




FIG. 27

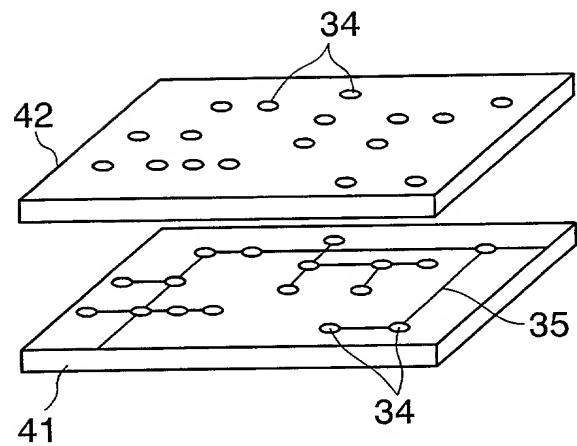


FIG. 28

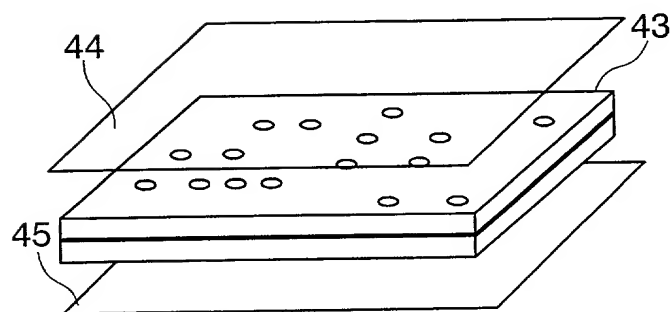


FIG. 29

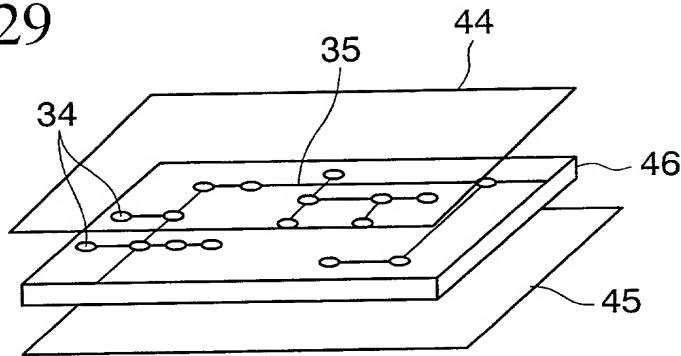


FIG. 30

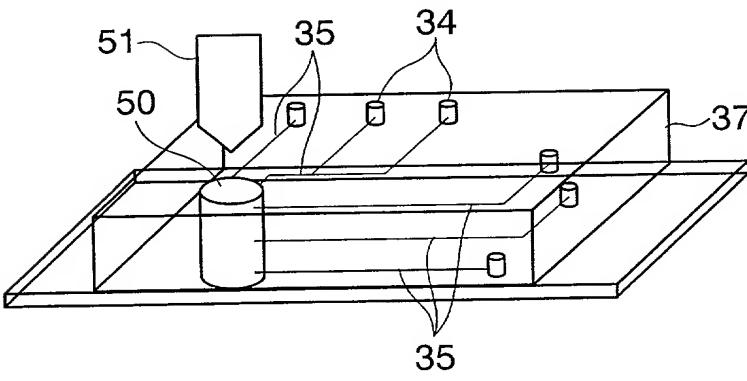


FIG. 31

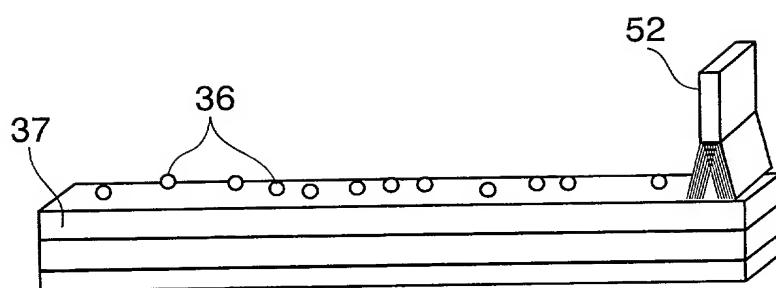


FIG. 32

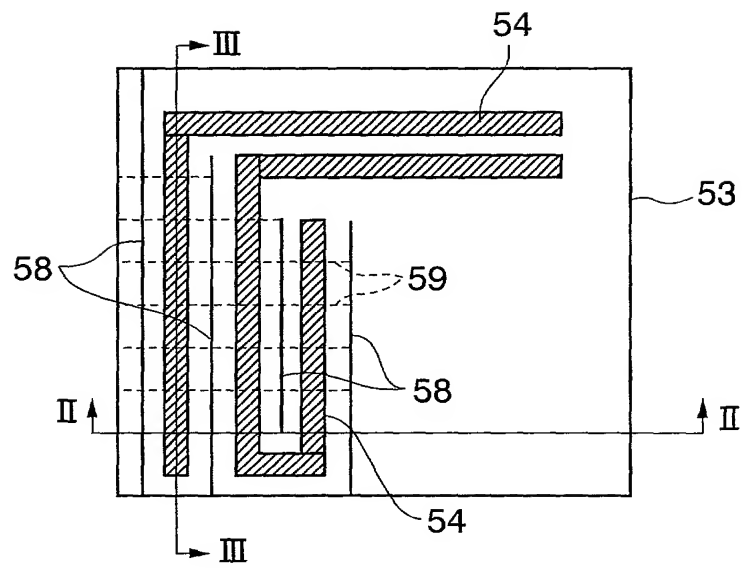


FIG. 33

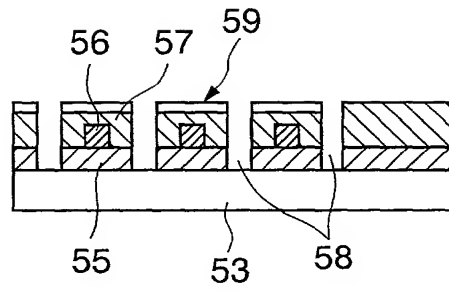
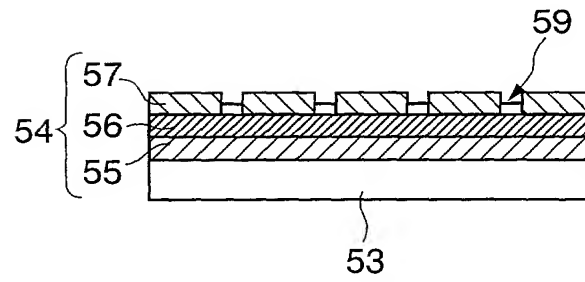


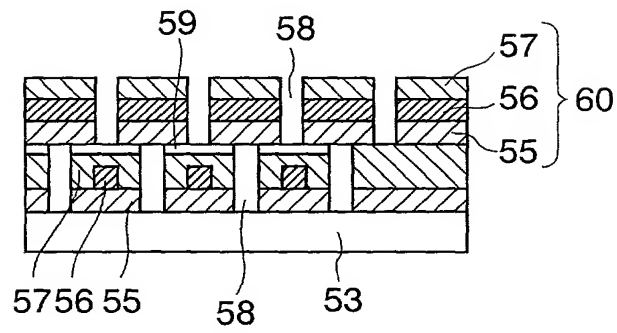
FIG. 34

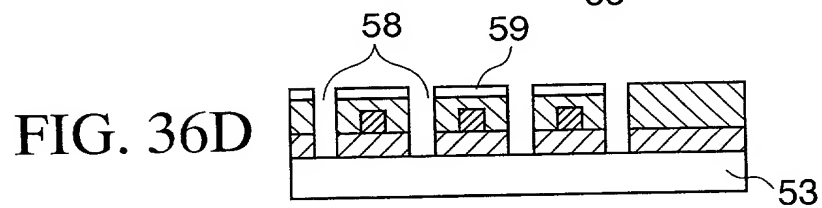
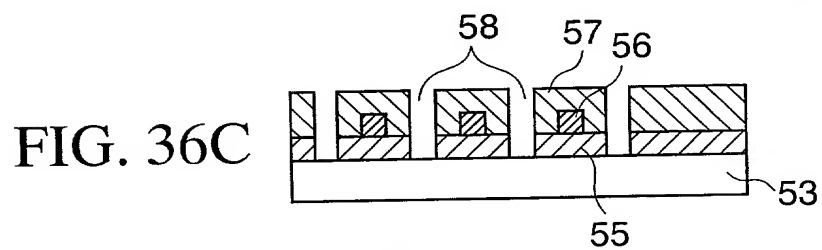
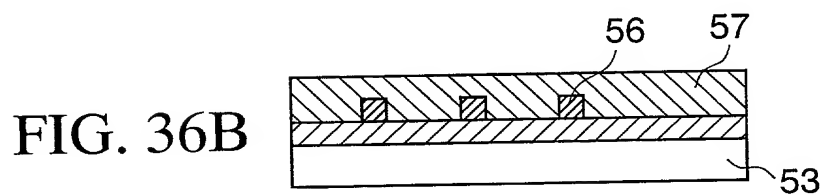
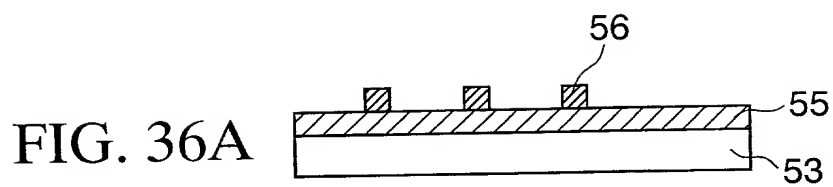


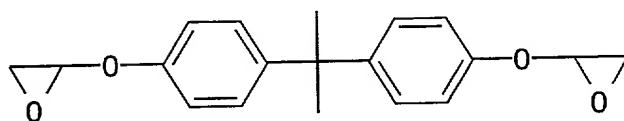


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FIG. 35

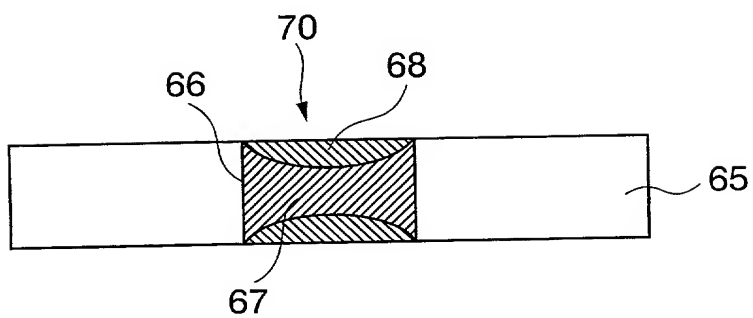






## 1 Bisphenol A Diglycidyl

FIG. 38



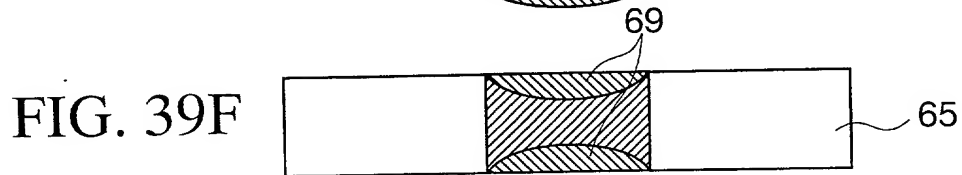
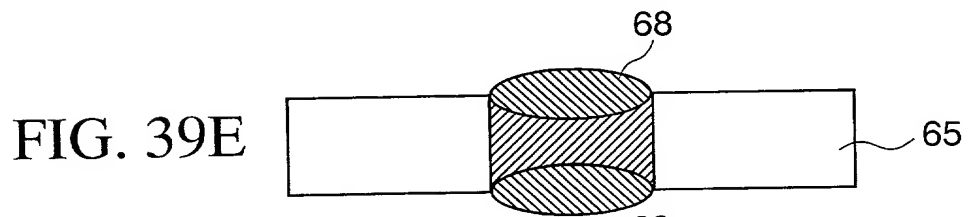
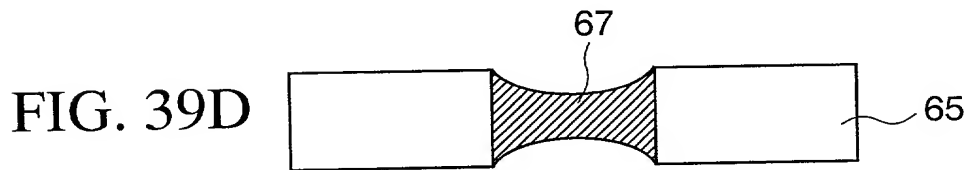
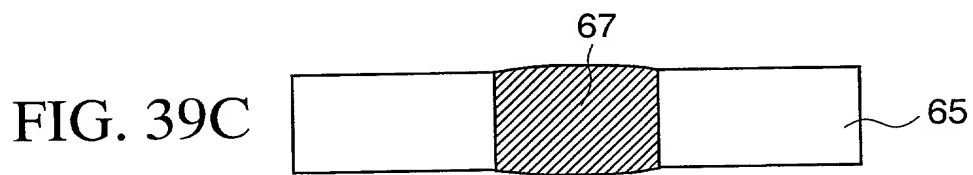
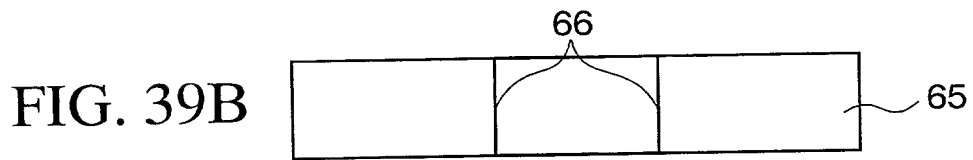
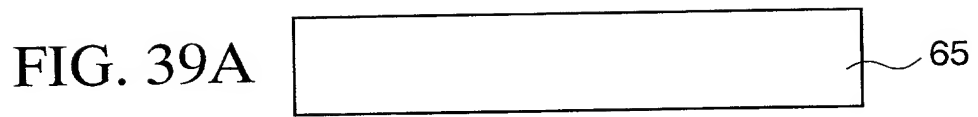


FIG. 40

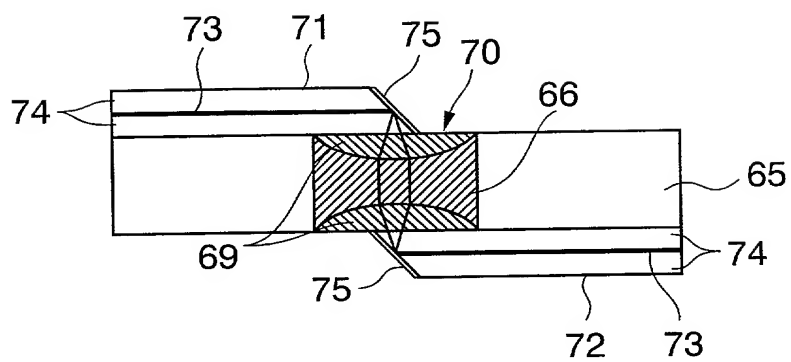


FIG. 41A

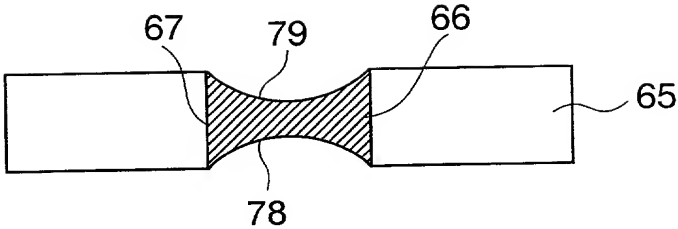


FIG. 41B

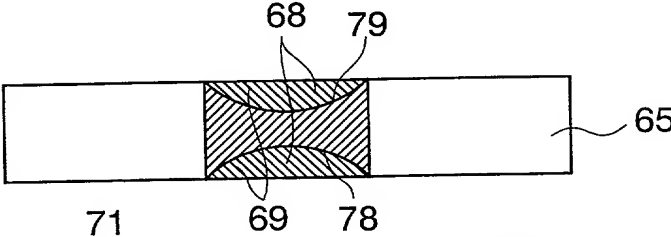


FIG. 41C

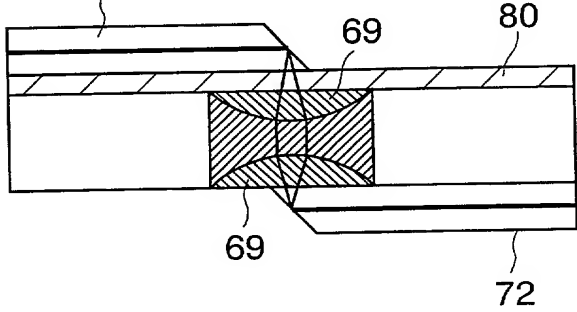


FIG. 42A

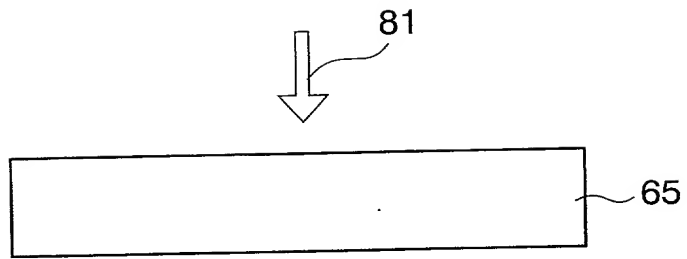


FIG. 42B

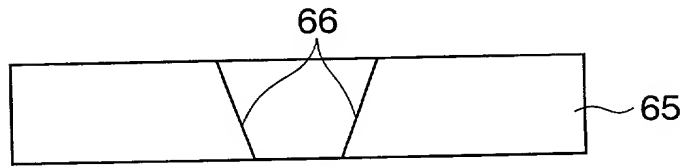


FIG. 42C

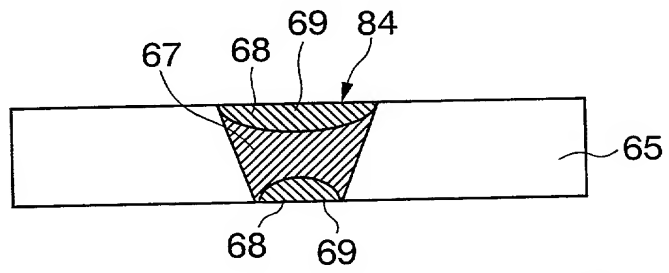


FIG. 42D

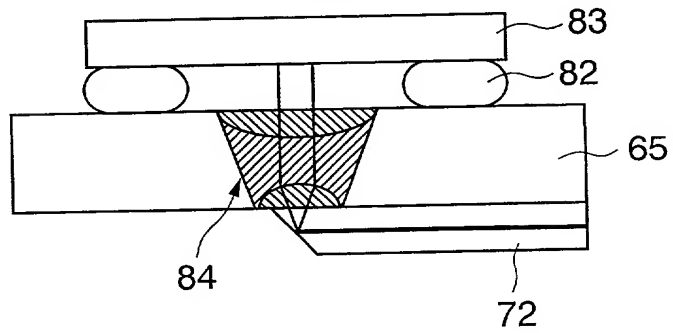




FIG. 43A

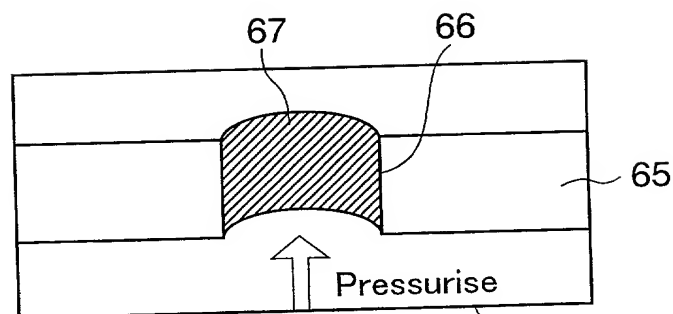


FIG. 43B

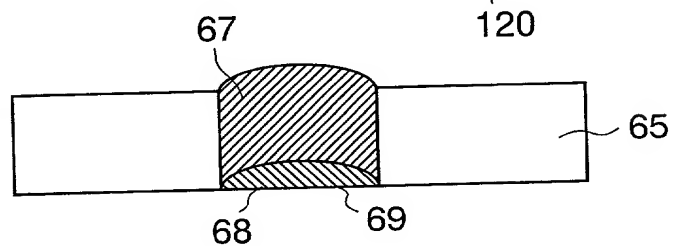


FIG. 43C

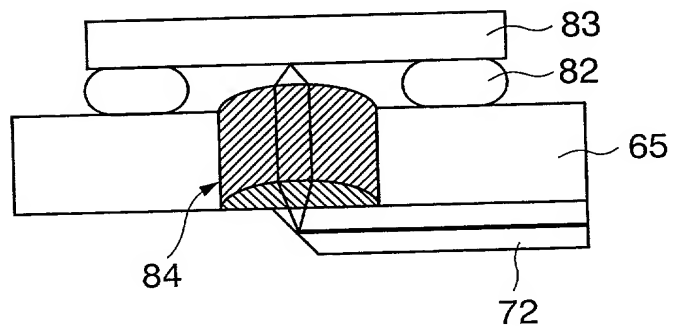


FIG. 44

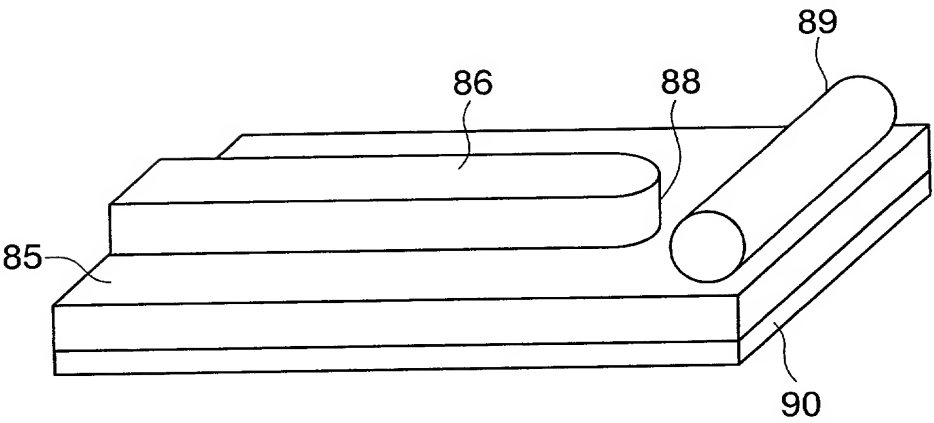
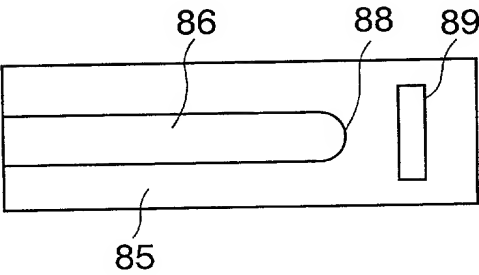


FIG. 45



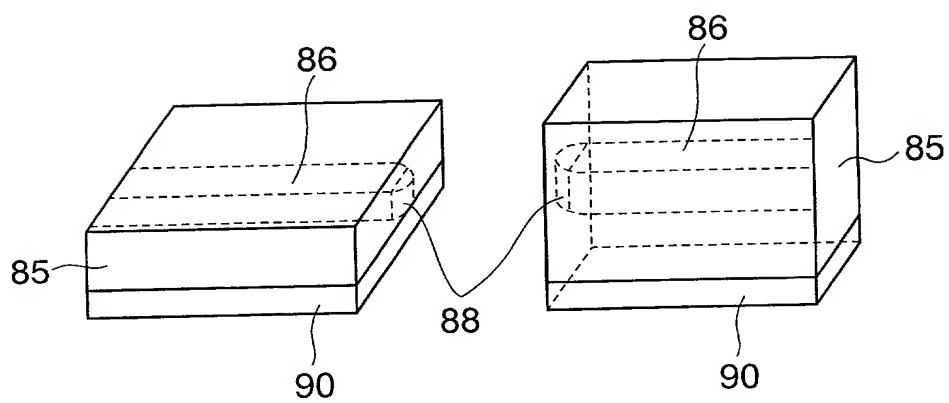


FIG. 48

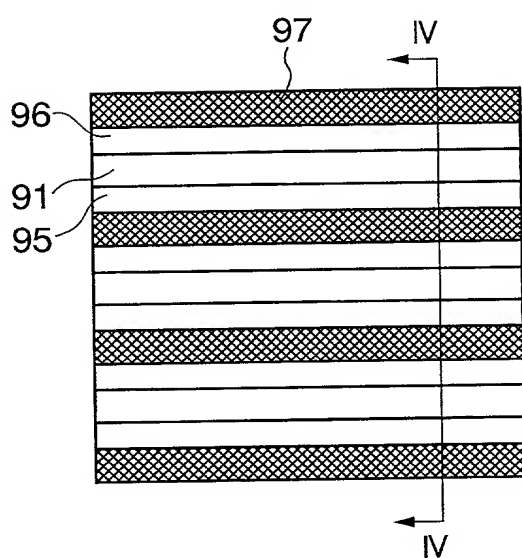


FIG. 49

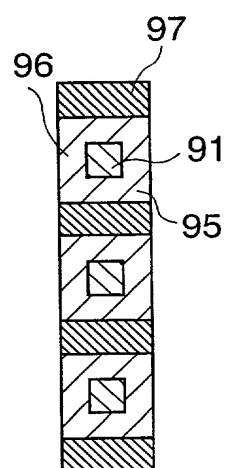


FIG. 50

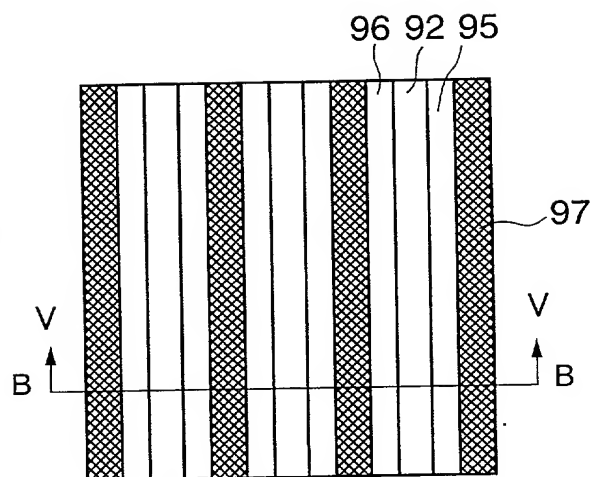


FIG. 51

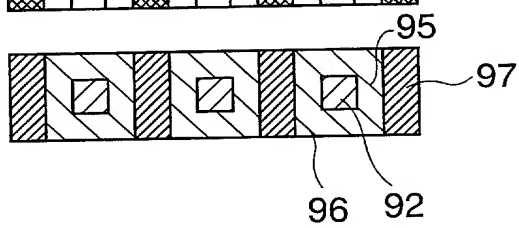




FIG. 55A



FIG. 55B

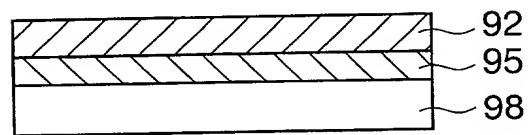


FIG. 55C

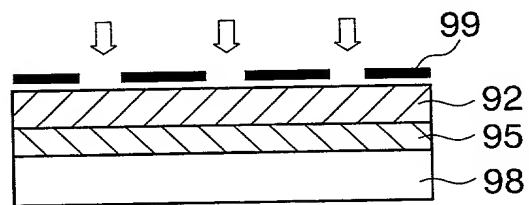
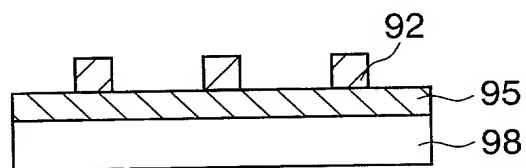


FIG. 55D



A cross-sectional view of a substrate assembly. A substrate 98 is shown with a patterned layer 95 on its top surface. The patterned layer 95 consists of a series of rectangular blocks 92 separated by recessed regions 96. The blocks 92 are connected to the substrate 98 by a layer of solder 94.

A cross-sectional view of a semiconductor device. It shows a substrate 98 at the bottom, followed by a layer 95. On top of layer 95 is a patterned layer 96. The layer 96 has several rectangular openings 92. The top surface of the device is a wavy, textured layer 97.



FIG. 56

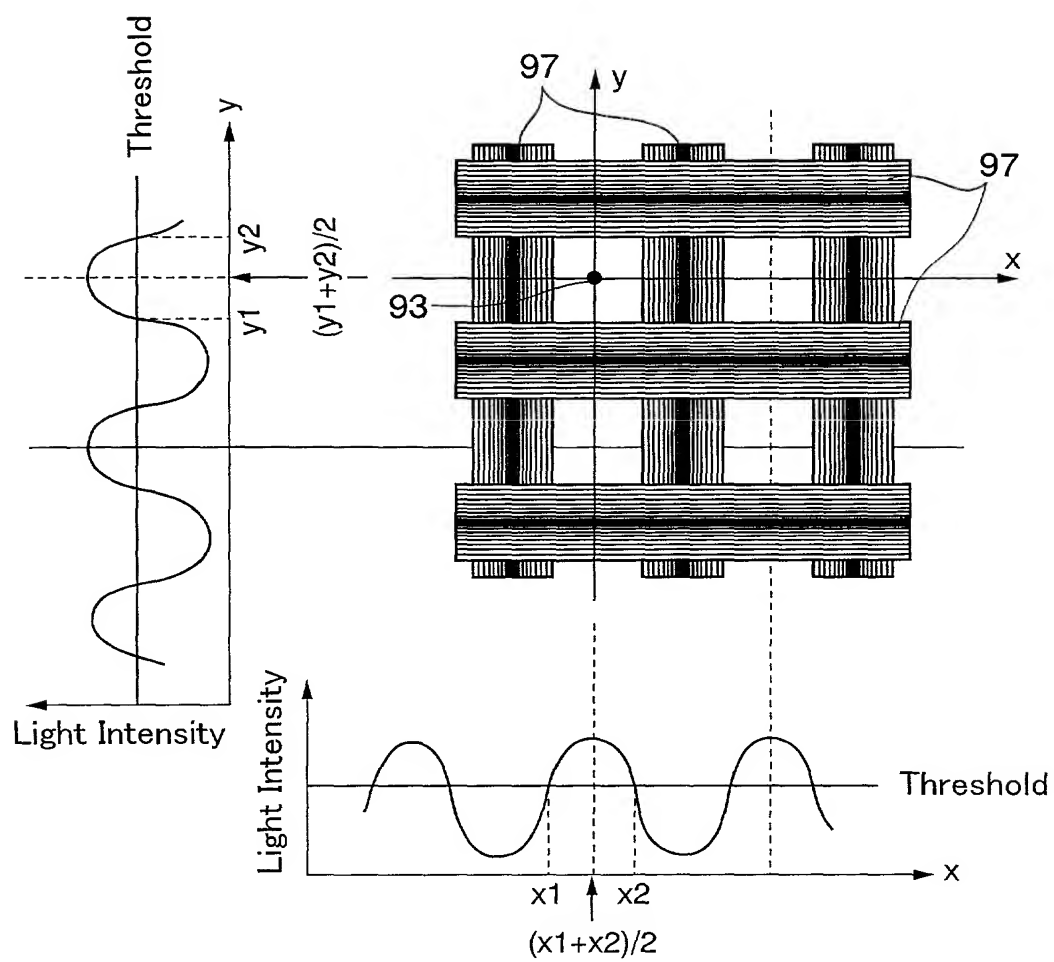


FIG. 57

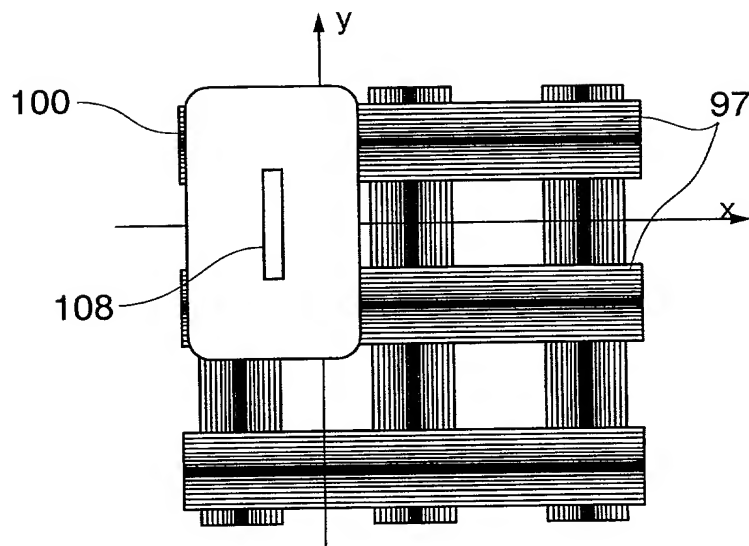


FIG. 58

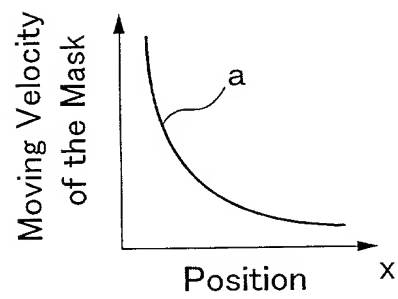


FIG. 59

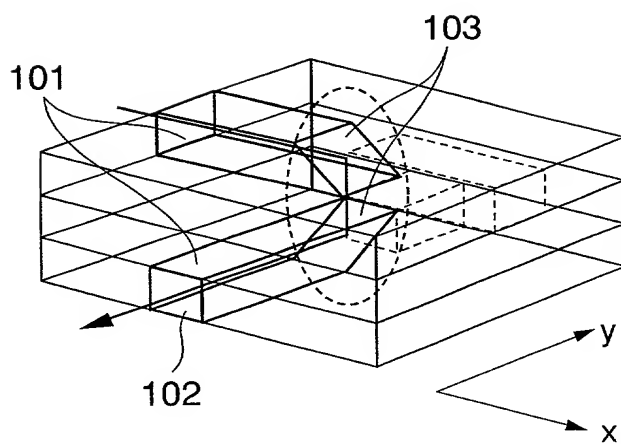




FIG. 62

